



GT150HH65T5H

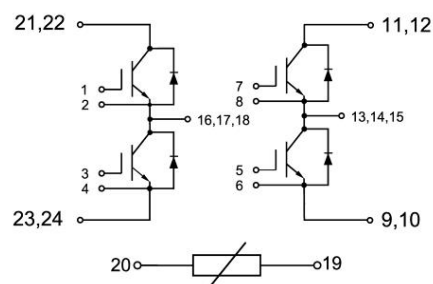
IGBT Module

Preliminary Data

Features:

- Trench & Field Stop IGBT
- Short Circuit Rated > 10 μ s
- Low Saturation Voltage
- Low Switching Loss
- 100% RBSOA Tested (2 $\times$ I_C)
- Low Stray Inductance
- Lead Free, Compliant with RoHS Requirement

Circuit Diagram



Applications:

- Industrial Inverters
- Servo Applications

IGBT, Inverter

Maximum Rated Values (T_C=25°C unless otherwise specified)

V _{CES}	Collector-Emitter Blocking Voltage	T _J =25°C	650	V
V _{GES}	Gate-Emitter Voltage		±20	V
I _C	Continuous Collector Current	T _C =100°C	150	A
		T _C =25°C	300	A
I _{CM}	Peak Collector Current Repetitive	t _p =1ms	300	A
P _D	Maximum Power Dissipation per IGBT	T _C =25°C T _{Jmax} =175°C	566	W



Electrical Characteristics of IGBT ($T_C=25^{\circ}\text{C}$ unless otherwise specified)

Static Characteristics

Symbol	Description	Conditions	Min.	Typ.	Max.	Units
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=2\text{mA}$, $V_{CE}=V_{GE}$	4.0	4.7	5.4	V
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C=150\text{A}$, $V_{GE}=15\text{V}$	$T_J=25^{\circ}\text{C}$	1.35	1.65	V
			$T_J=125^{\circ}\text{C}$	1.45		V
			$T_J=150^{\circ}\text{C}$	1.50		V
I_{CES}	Collector-Emitter Leakage Current	$V_{GE}=0\text{V}$, $V_{CE}=V_{CES}$, $T_J=25^{\circ}\text{C}$			1	mA
I_{GES}	Gate-Emitter Leakage Current	$V_{GE}=\pm 20\text{V}$, $V_{CE}=0\text{V}$, $T_J=25^{\circ}\text{C}$			200	nA
C_{ies}	Input Capacitance	$V_{CE}=25\text{V}$, $V_{GE}=0\text{V}$, $f=100\text{kHz}$		10.4		nF
C_{oes}	Output Capacitance			0.62		nF
C_{res}	Reveres Transfer Capacitance			0.22		nF

Switching Characteristics

$t_{d(on)}$	Turn-on Delay Time	$V_{CC}=300V, I_C=150A,$ $R_G=6.8\Omega, V_{GE}=\pm 15V,$ Inductive Load	$T_J=25^{\circ}C$		276		ns
			$T_J=125^{\circ}C$		283		
			$T_J=150^{\circ}C$		307		
t_r	Rise Time		$T_J=25^{\circ}C$		131		ns
			$T_J=125^{\circ}C$		132		
			$T_J=150^{\circ}C$		142		
$t_{d(off)}$	Turn-off Delay Time		$T_J=25^{\circ}C$		314		ns
			$T_J=125^{\circ}C$		316		
			$T_J=150^{\circ}C$		331		
t_f	Fall Time		$T_J=25^{\circ}C$		137		ns
			$T_J=125^{\circ}C$		154		
			$T_J=150^{\circ}C$		157		
E_{on}	Turn-on Switching Loss	$V_{CC}=300V, I_C=150A,$ $R_G=6.8\Omega, V_{GE}=\pm 15V,$ $di/dt=968A/\mu s(T_J=150^{\circ}C),$ Inductive Load	$T_J=25^{\circ}C$		2.5		mJ
		$T_J=125^{\circ}C$		2.8			
		$T_J=150^{\circ}C$		3.1			



E _{off}	Turn-off Switching Loss	V _{CC} =300V, I _C =150A, R _G =6.8Ω, V _{GE} =±15V, du/dt=2923V/μs(T _J =150°C), Inductive Load	T _J =25°C		4.0		mJ
			T _J =125°C		5.3		
			T _J =150°C		5.7		
Q _g	Total Gate Charge	V _{GE} =+15V...-15V	T _J =25°C		750		nC
R _{g internal}	Internal Gate Resistor				2.0		Ω
SCSOA	V _{CC} =300V, V _{GE} =+/-15V, T _J =150°C			10			μs
R _{θJC}	IGBT Thermal Resistance: Junction-to-Case (per IGBT)					0.26	°C/W

FWD, Inverter

Maximum Rated Values (T_C=25°C unless otherwise specified)

V _{RRM}	Repetitive peak reverse voltage	T _J =25°C	650	V
I _F	Diode Continuous Forward Current		150	A
I _{FM}	Peak FWD Current Repetitive	t _p =1ms	300	A

Electrical Characteristics of Diode (T_C=25°C unless otherwise specified)

Symbol	Description	Conditions		Min.	Typ.	Max.	Units
V _{FM}	Forward Voltage	I _F =150A	T _J =25°C		1.52		V
			T _J =125°C		1.55		
			T _J =150°C		1.53		
t _{rr}	Reverse Recovery Time	I _F =150A, -diF/dt=882A/μs(T _J =150°C), V _{rr} =300V, V _{GE} =-15V	T _J =25°C		133		ns
			T _J =125°C		166		
			T _J =150°C		178		
I _{rr}	Peak Reverse Recovery Current		T _J =25°C		45		A
			T _J =125°C		69		
			T _J =150°C		75		
Q _{rr}	Reverse Recovery Charge		T _J =25°C		3.47		μC
			T _J =125°C		7.08		
			T _J =150°C		8.23		



E _{rec}	Reverse Recovery Energy	I _F =150A, -diF/dt=882A/μs(T _J =150°C), V _{rr} =300V, V _{GE} =-15V	T _J =25°C		0.33		mJ
			T _J =125°C		1.04		
			T _J =150°C		1.53		
R _{θJC}	Thermal Resistance: Junction-to-Case (per Diode)					0.36	°C/W

Internal NTC-Thermistor Characteristics

Symbol	Description	Min.	Typ.	Max.	Units
R ₂₅	T _C =25°C		5		kΩ
ΔR/R	T _C =100°C, R ₁₀₀ =465Ω	-5		5	%
P ₂₅	T _C =25°C			10	mW
B _{25/50}	$R_2=R_{25} \exp[B_{25/50}(1/T_2-1/(298.15K))]$		3380		K
B _{25/80}	$R_2=R_{25} \exp[B_{25/80}(1/T_2-1/(298.15K))]$		3440		K
B _{25/100}	$R_2=R_{25} \exp[B_{25/100}(1/T_2-1/(298.15K))]$		3545		K

Module

Symbol	Description		Min.	Typ.	Max.	Units
V _{iso}	Isolation Voltage (All Terminals Shorted)	RMS, f=50Hz, 1mintue	2500			V
Internal Isolation			Al ₂ O ₃			
T _J	Maximum Junction Temperature				175	°C
T _{JOP}	Maximum Operating Junction Temperature Range		-40		+150	°C
T _{stg}	Storage Temperature		-40		+125	°C
CTI	Comparative Tracking Index		200			
R _{θCS}	Case-to-Sink Thermally (Conductive Grease Applied)				0.04	°C/W
M	Mounting Screw:M5		3.0		6.0	N·m
G	Weight			190		g



Ordering Information Table

Device code

G	T	150	HH	65	T5	H
①	②	③	④	⑤	⑥	⑦

- ① - IGBT Module
- ② - Trench, Low Switching Losses IGBT
- ③ - Rated Current (150=150A)
- ④ - Circuit Configuration: HH (H Bridge)
- ⑤ - Rated Voltage (65=650V)
- ⑥ - Package Type
- ⑦ - Test Level (Pass the Important Reliability Test-Industrial Grade)

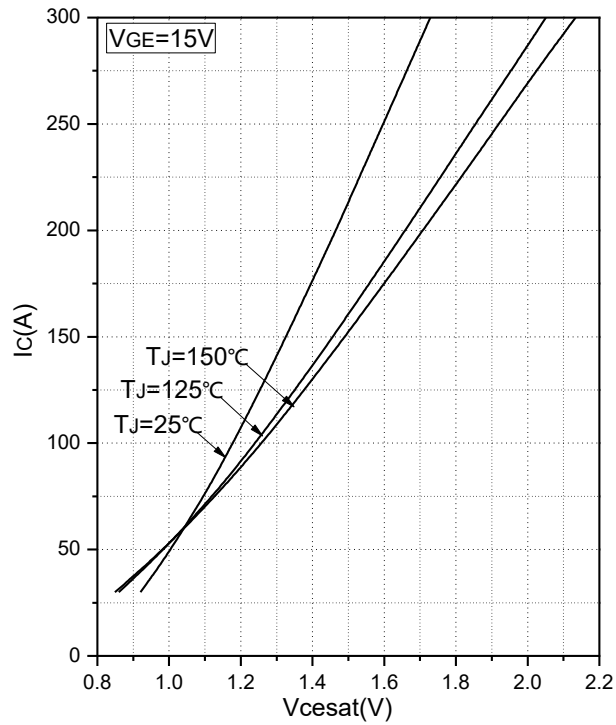


Fig.1 Typical Saturation Voltage Characteristics

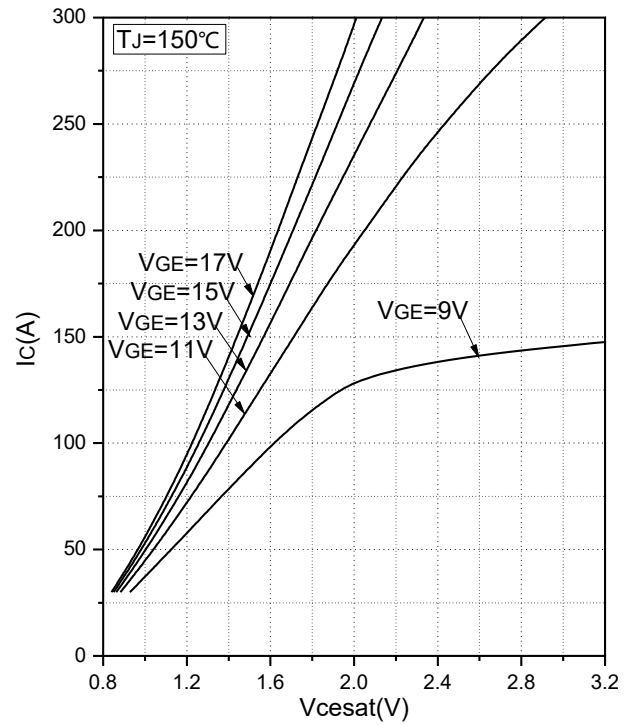


Fig.2 Typical Output Characteristics

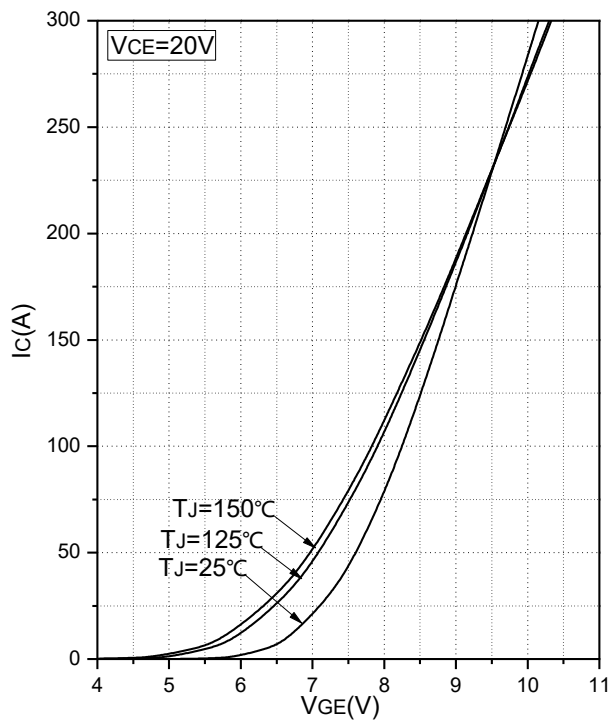


Fig.3 Transfer Characteristic

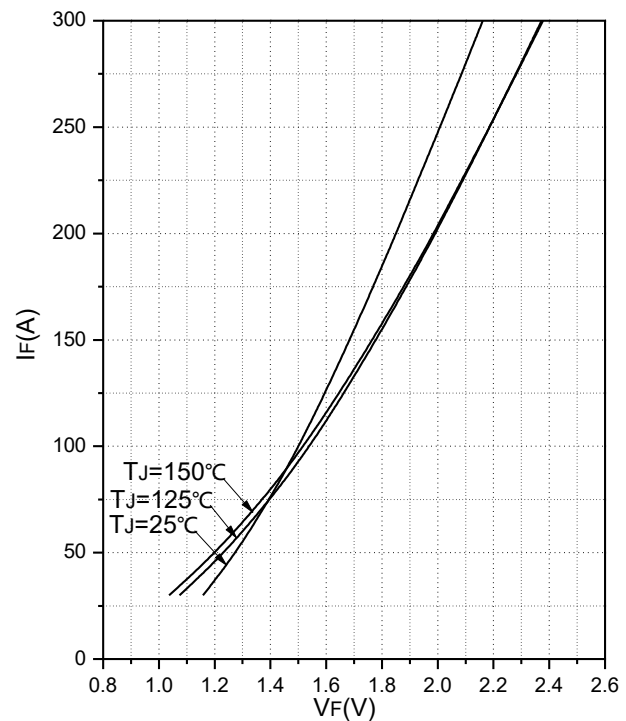


Fig.4 Forward Characteristics of Diode

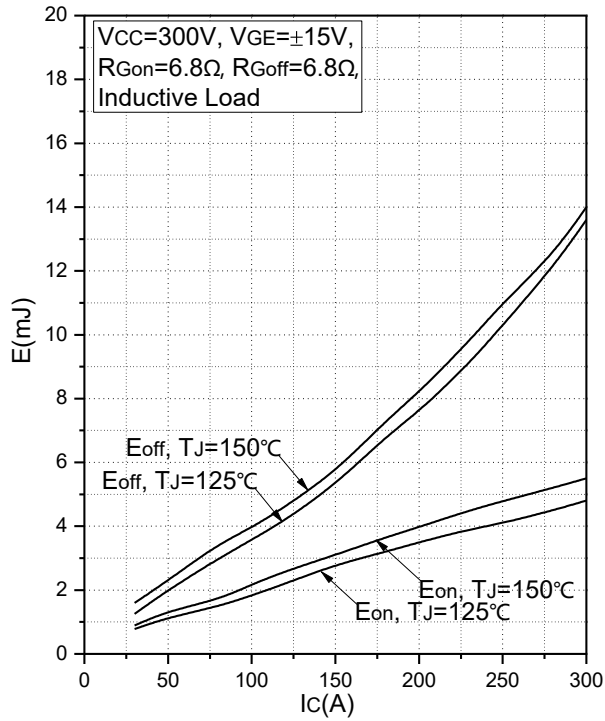


Fig.5 Typical Switching Loss vs. Collector Current

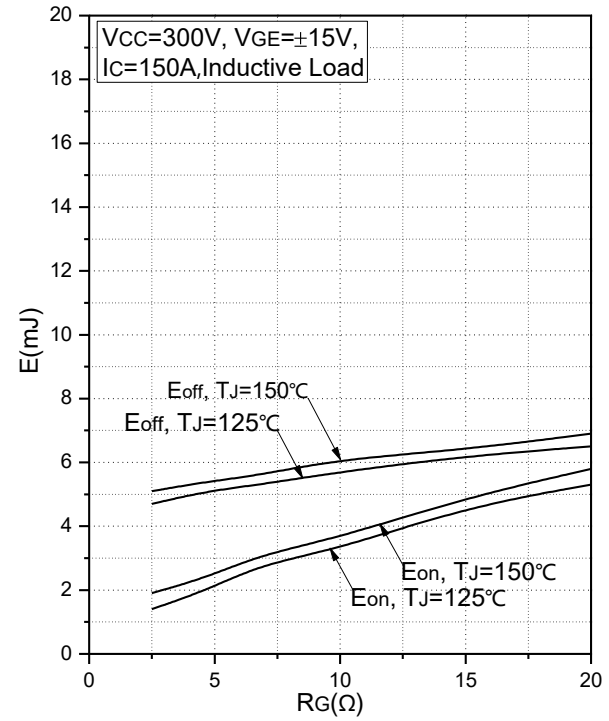


Fig.6 Typical Switching Loss vs. Gate Resistance

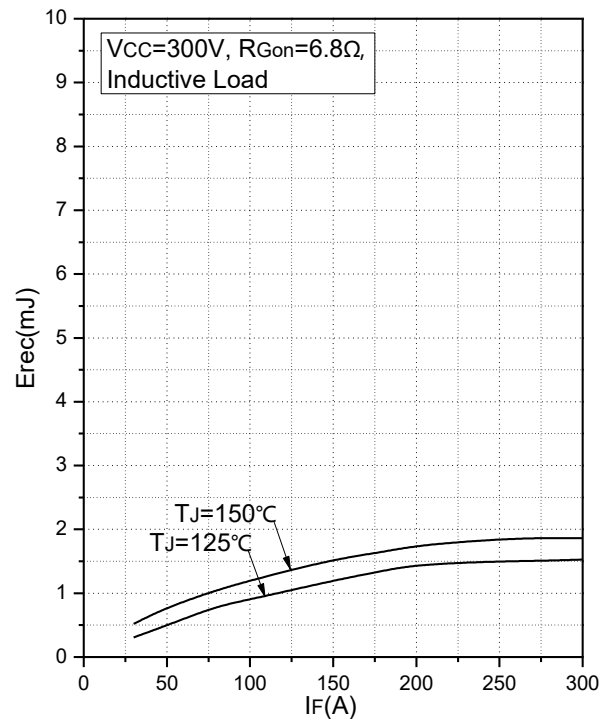


Fig.7 Typical Switching Losses vs. Forward Current

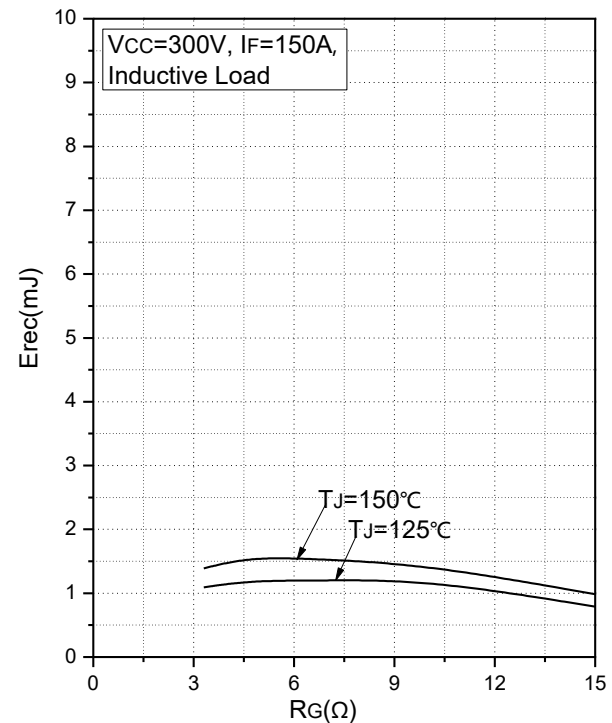


Fig.8 Typical Switching Loss vs. Gate Resistance

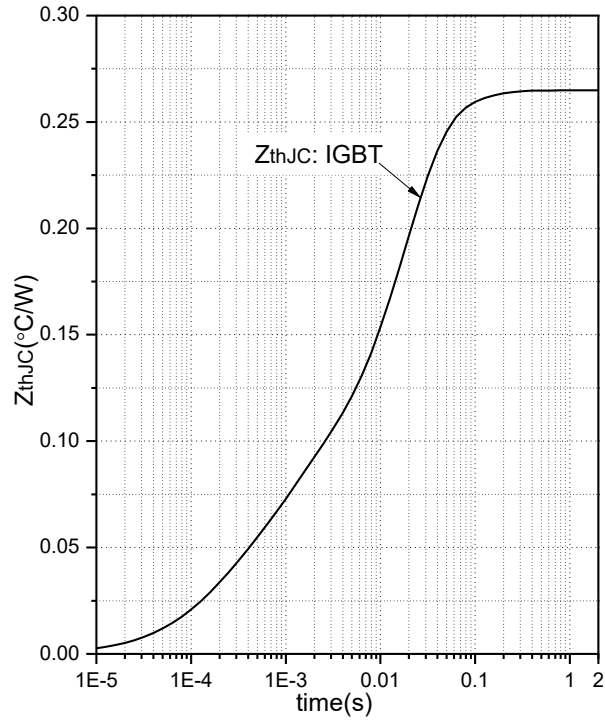


Fig.9 Transient Thermal Impedance (IGBT)

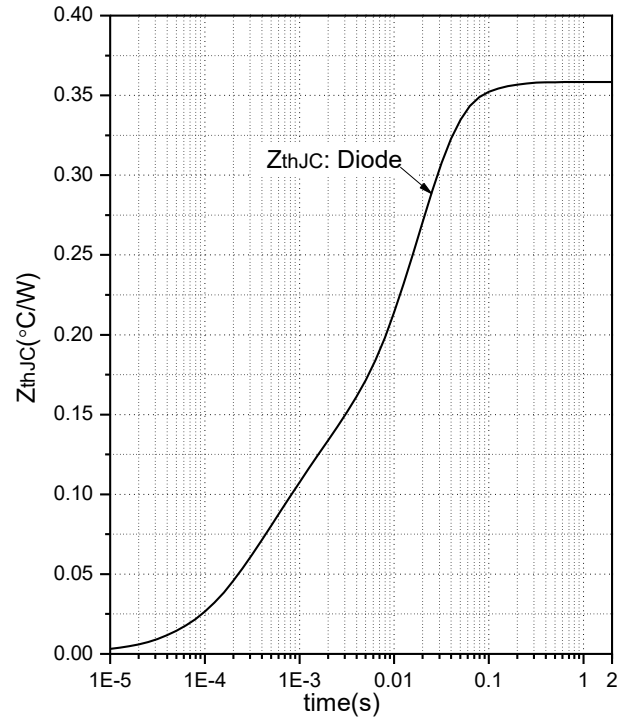


Fig.10 Transient Thermal Impedance (Reverse Diode)

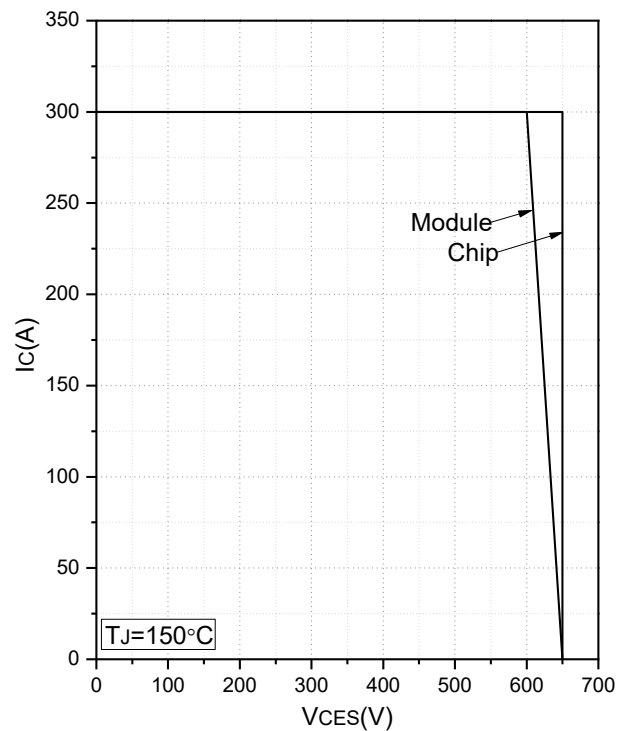


Fig.11 Reverse Bias Safe Operation Area (RBSOA)

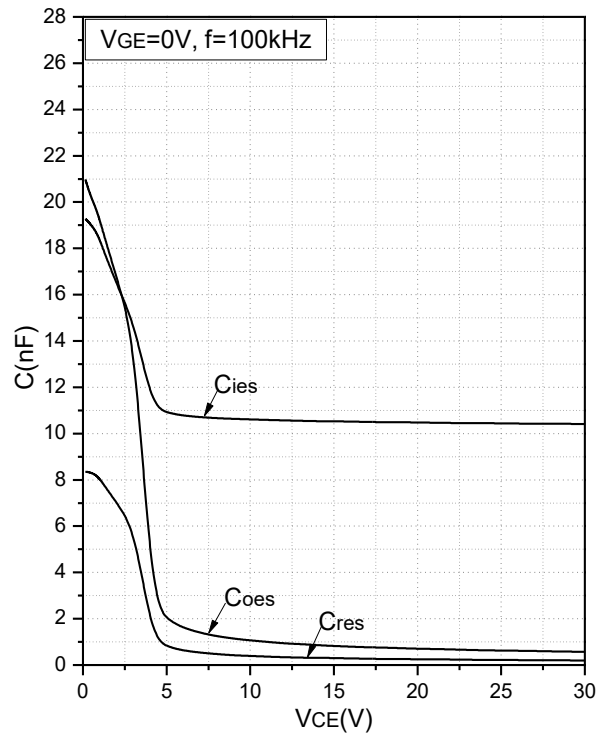


Fig.12 Capacitance Characteristics

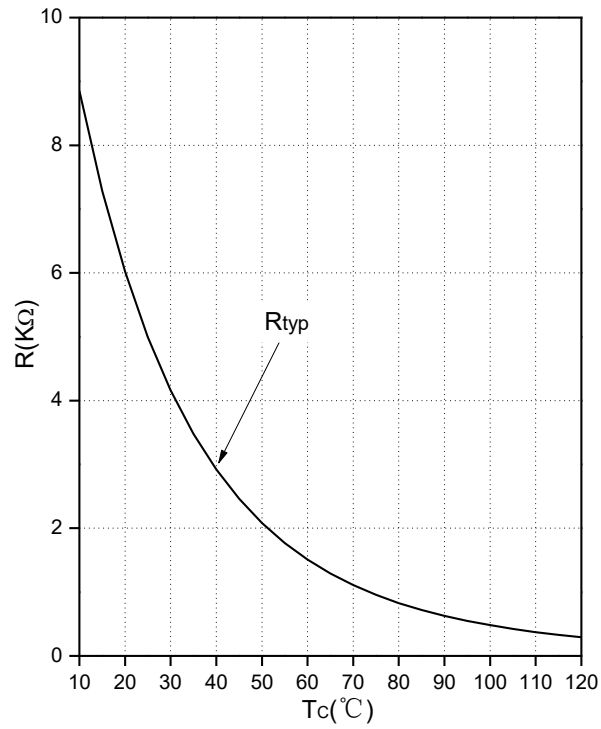
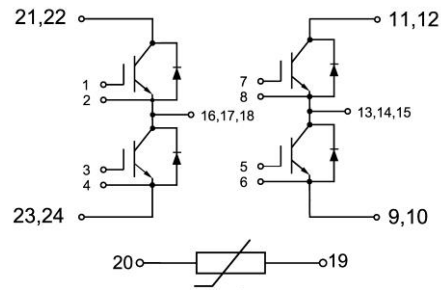


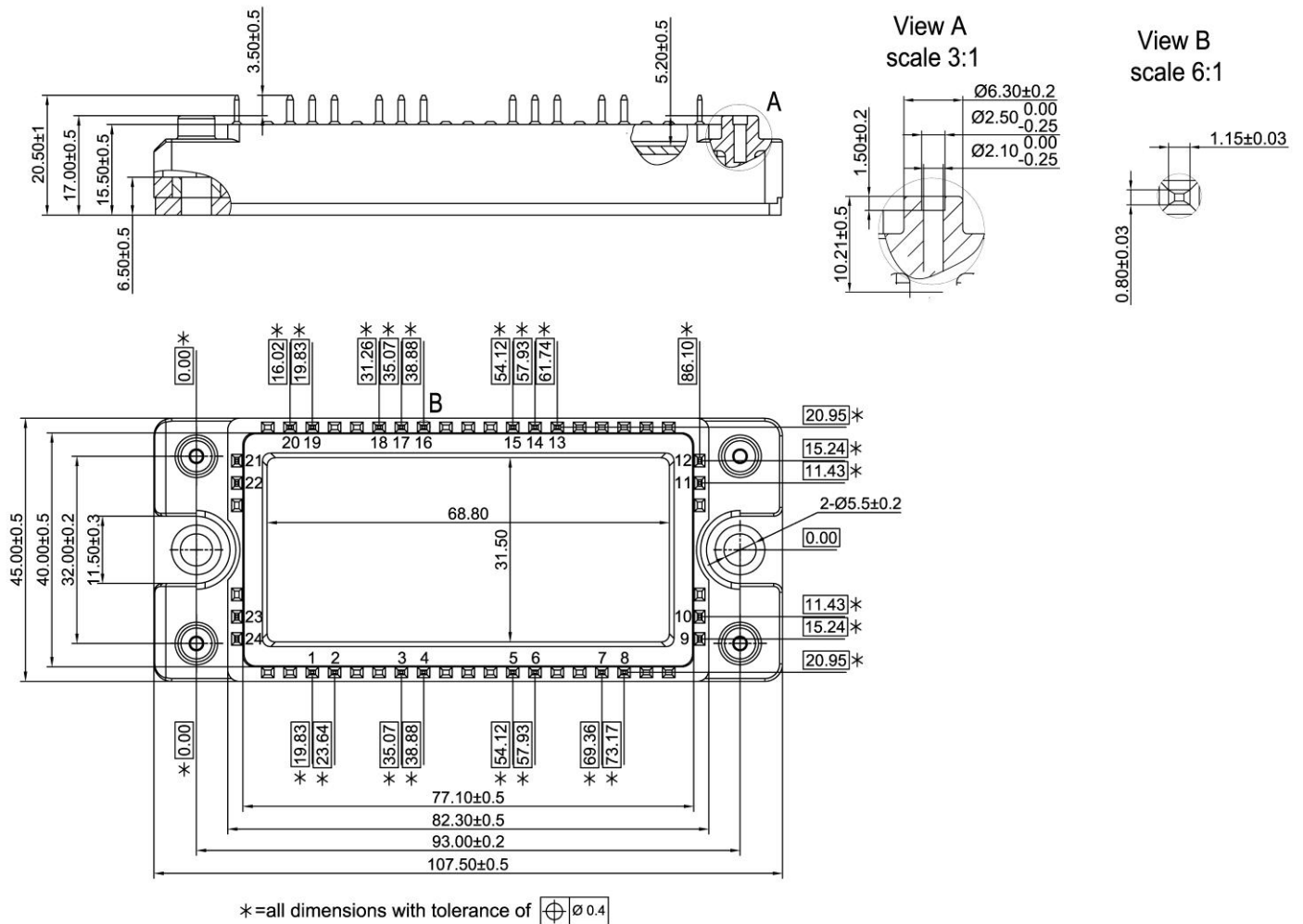
Fig.13 NTC Temperature Characteristics



Internal Circuit:



Package Outline (Unit: mm):





Revision	Notes
01	Initial Release

Announcement

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